IEEE/ASIME International Conference on

Advanced Intelligent Mechatronics
July8-12,2019 | Hong Kong Science Park, Hong Kong, China

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Call for Papers

The 2019 IEEE/ASME International Conference on Advanced Intelligent Mechatronics (AIM 2019) will be held on July 8 -12, 2019 in Hong Kong Science Park, Hong Kong, China. As a flagship conference

> focusing on mechatronics and intelligent systems, the AIM 2019 will bring together an international community of experts to discuss the state-of-the-art, new research results, perspectives of future developments, and innovative applications relevant to mechatronics, robotics, automation, industrial electronics, and related areas.

The sponsors and organizers of AIM 2019 invite a submission of high quality mechatronics research papers describing original work, including but not limited to the following topics: Actuators, Automotive Systems, Bioengineering, Data Storage Systems, Electronic Packaging, Fault Diagnosis, Human-Machine

interfaces, Industry Applications, Information Technology, Intelligent Systems, Machine Vision, Manufacturing, Micro-Electro-Mechanical Systems, Micro/Nano Technology, Modeling and Design, System Identification and Adaptive Control, Motion Control, Vibration and Noise Control, Neural and Fuzzy Control, Opto-Electronic Systems, Optomechatronics, Prototyping, Real-Time and Hardware-in-the-Loop Simulation, Robotics, Sensors, System Integration, Transportation Systems, Smart Materials and Structures, Energy Harvesting, and other frontier fields.

All contributed and invited papers, tutorial and workshop proposals, and invited and special session proposals must be uploaded through the submission website (www.aim2019.org) according to the deadlines below.

Contributed & Invited Papers: All papers go through a rigorous review process. Accepted papers will be presented by their authors at the conference. All accepted peer-reviewed manuscripts will be published in the conference proceedings, and will be submitted for inclusion in IEEEXplore, subject to formatting and copyright requirements.

Tutorials & Workshops: Proposals are invited for half-day or full-day tutorials and workshops. Workshops explore the frontiers of recent or emerging topics in mechatronics, while tutorials provide a foundation for future self-study in important area of mechatronics. Tutorial and workshop proposals must include: (1) a statement of objectives, (2) a description of the intended audience, and (3) a list of speakers with an outline of their planned presentations. Unless specifically requested, individual tutorial and workshop presentations are not peer reviewed, and do not appear in the proceedings.

Invited & Special Sessions: Proposals are invited for invited and special sessions. Invited sessions consist of 4 to 6 thematically related invited papers. Invited session proposals consist of a brief statement of purpose and extended abstracts of the included invited papers. Invited papers are submitted and reviewed following the same process as contributed papers, and are included in the proceedings.

TMECH Focused Sections on Selected AIM Papers

Selected papers of AIM 2019 will be invited to submit an extended version to IEEE/ASME Transactions Mechatronics (TMECH) for publication consideration in an AIM Focused Section to be published in 2020. The extended version submitted to TMECH should contain sufficient and recognizable new innovation, contribution, result, and material from the 2019 AIM paper.

Important Dates

Submission of Special & Invited Session Proposals Submission of Tutorial & Workshop Proposals Submission of Contributed & Invited Papers Notification of Paper Status Final Paper Submission Advanced Registration

*All deadlines are 23:59 PST.

February 10, 2019 February 10, 2019 February 28, 2019

> April 25, 2019 May 15, 2019

May 28, 2019











